Figure 3. Pin Configuration (Top View)

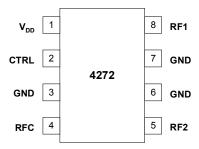


Table 2. Pin Descriptions

Pin No.	Pin Name	Description		
1	V_{DD}	Nominal +3 V supply connection.		
2	CTRL	CMOS logic level: High = RFC to RF1 signal path Low = RFC to RF2 signal path		
3	GND	Ground connection. Traces should be physically short and connected to ground plane for best performance.		
4	RFC	RF Common port		
5	RF2	RF2 port. ⁴		
6	GND	Ground Connection Traces should be physically short and connected to ground plane for best performance		
7	GND	Ground Connection. Traces should be physically short and connected to ground plane for best performance.		
8	RF1	RF1 port.4		

oins must be blocked with an ext Note: 4. All R series' acitor or h at 0 V_{DC}.

Table 3. Operating Ranges

Parameter	Min	Typ	Max	Units
V _{DD} Power Supply Voltage	2.7	3.0	3.3	V
I_{DD} Power Supply Current $(V_{DD} = 3 \text{ V}, \text{ CTRL} = 4 \text{ V})$		8	20	μΑ
Operating temperature range	-40		85	°C
Control Voltage High	$0.7xV_{DD}$			V
Control Voltage Low			$0.3xV_{DD}$	V

Table 4. Absolute Maximum Ratings

Symbol	Parameter/Conditions	Min	Max	Units
V_{DD}	Power supply voltage	-0.3	4.0	V
Vı	Voltage on any input	-0.3	V _{DD} + 0.3	V
T _{ST}	Storage temperature range	-65	150	°C
$P_{\scriptscriptstyle IN}$	Input power (50·Ω)		34	dBm
V_{ESD}	FSD voltage (HBM, ML_STD 883 Method 3015.7)		1500	٧

Maximum Ratings are thos ted in the above table. Exceeding may cause permanent device damag Functional operation should be restricted to the mits in the Operating Ranges table. Exposure to bsolute maximum ratings for extended periods may affect device reliability.

Latch-Up Avoidand

Unlike conventional CMOS devices, UltraCMOS™ devices are immune to latch-up.

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS™ device, observe the same precautions that you would use with ther ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the rating specified in Table 4.



Table 5. Single-pin Control Logic Truth Table

Control Voltages	Signal Path	
Pin 1 $(V_{DD}) = V_{DD}$ Pin 2 $(CTRL) = High$	RFC to RF1	
Pin 1 $(V_{DD}) = V_{DD}$ Pin 2 $(CTRL) = Low$	RFC to RF2	

Table 6. Complementary-pin Control Logic **Truth Table**

Control Voltages	Signal Path		
Pin 1 $(V_{DD}) = Low$ Pin 2 $(CTRL) = High$	RFC to RF1		
Pin 1 (V _{DD}) = High Pin 2 (CTRL) = Low	RFC to RF2		

Control Logic Input

The PE4272 is a versatile RF CMOS switch that supports two operating control modes; single-pin control mode and complementary-pin control mode.

Single-pin control mode enables the switch to operate with a single control pin (pin 2) supporting a +3-volt CNOS logic input, and requires a dedicated +3-volt power supply connection (pin 1). This mode of operation reduces the number of control lines required and simplifies the switch ontrol interface typically derived from a CMOS uProcessor I/O port.

omplementary-pin control mode allows the witch to operate using complementary control in CTRL and V_{2D} (pins 2 & 1), that can be directly driven by 2-volt CMOS logic or a suitable Processor //O port. This enables the PE4272 to operate in positive control voltage mode within the PE4272 operating limits.



Evaluation Kit

The SPDT Switch Evaluation Kit board was designed to ease customer evaluation of the PE4272 SPDT switch. The RF common port is connected through a 75 Ω transmission line to the bottom F connector, J2. Port 1 and Port 2 are connected through 75 Ω transmission lines to two F connectors on either side of the board, J1 and J3. A through transmission line connects F connectors J4 and J5. This transmission line can be used to estimate the loss of the PCB over the environmental conditions being evaluated.

The board is constructed of a two metal layer FR4 material with a total thickness of 0.031". The bottom layer provides ground for the RF transmission lines. The transmission lines were designed using a coplanar waveguide with ground plane model using a trace width of 0.021", trace gaps of 0.030", dielectric thickness of 0.028", copper thickness of 0.0021" and ϵ_r of 4.3.

J6 provides a means for controlling the DC inputs to the device. The lower right pin (J6-2) is connected to the device CTRL input. The upper right pin is connected to the device V_{DD} input. Footprints for decoupling capacitors are provided on both and V_{DD} traces. It is the responsibility of t customer to determine proper supply decoupling for their design application. Removing these components from the evaluation k card has not b shown to deal ade RF erfor

Figure 4. Evaluation Board Layouts

Peregrine specification 101/0243

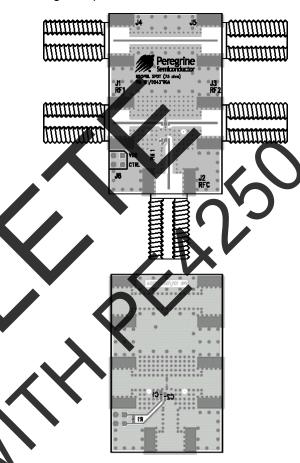
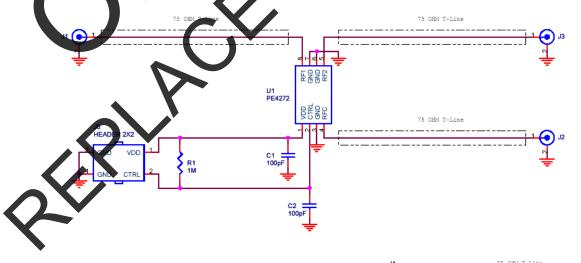


Figure 5. Evaluation Board Schematic Peregrine specification 102/0309



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Figure 6. Insertion Loss: RFC-RF1 @ 25 °C

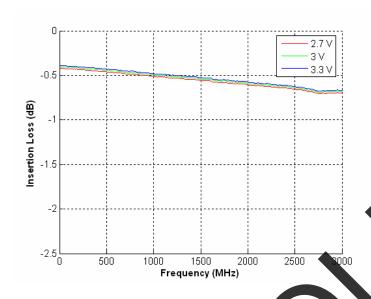


Figure 7. Insertion Loss: RFC-RF1 @ 3 V

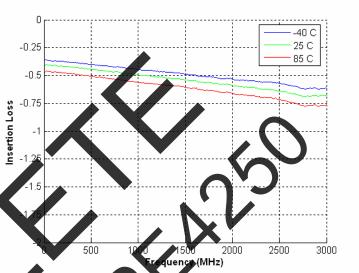
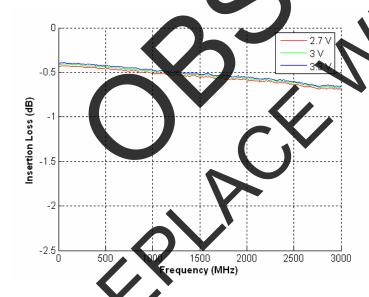


Figure 8. Insertion Loss: R @ 25 °C



9. Insertion Loss: RFC-RF2 @ 3 V

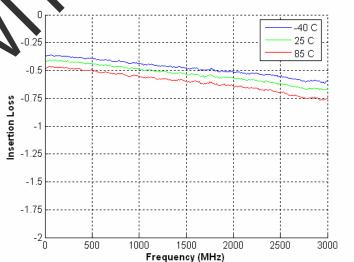




Figure 10. Isolation: RFC-RF1 @ 25 °C

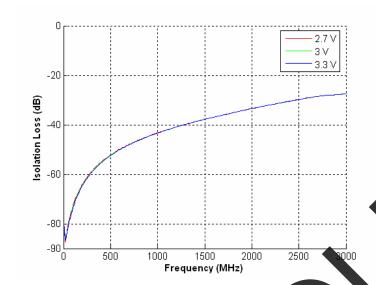


Figure 11. Isolation: RFC-RF1 @ 3 V

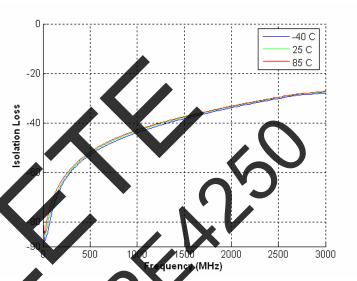
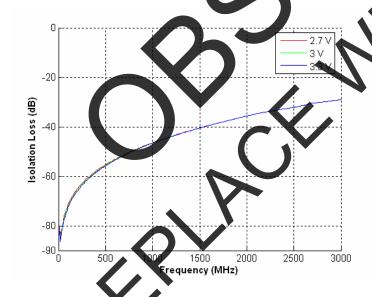


Figure 12. Isolation: RFC-R



13. Isolation: RFC-RF2 @ 3 V

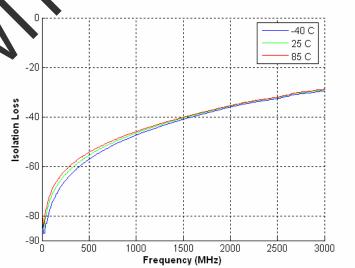




Figure 14. Isolation: RF1-RF2 @ 25 °C

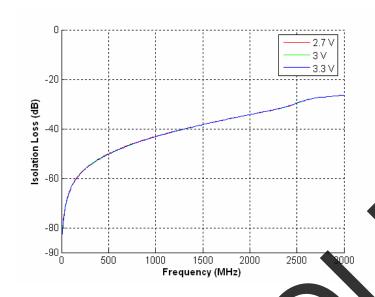


Figure 15. Isolation: RF1-RF2 @ 3 V

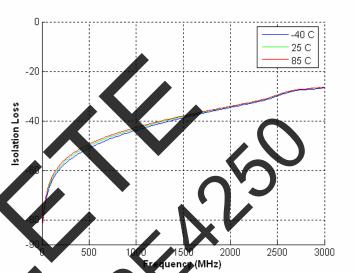


Figure 16. Return Loss: RFC-RF1

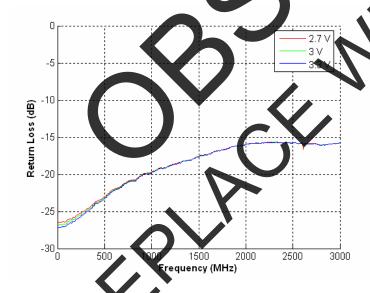


Figure 17. Return Loss: RFC-RF1 @ 3 V

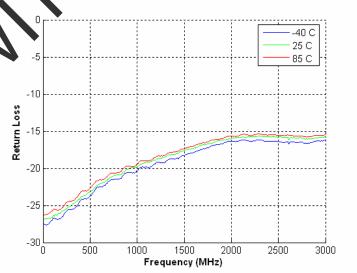




Figure 18. Return Loss: RFC-RF2 @ 25 °C

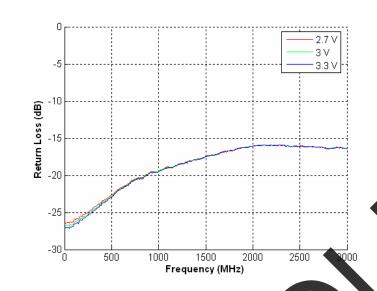


Figure 19. Return Loss RFC-RF2 @ 3 V

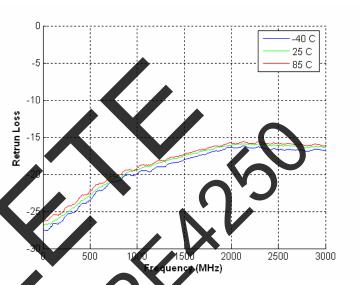
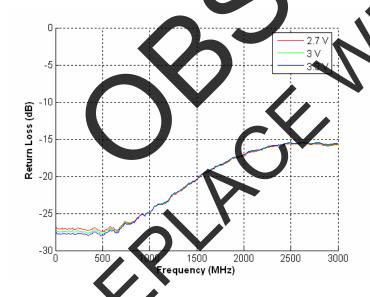


Figure 20. Return Loss: RFC-RF1/RF2 @ 25 °C



21. Return Loss: RFC-RF1/RF2 @ 3 V

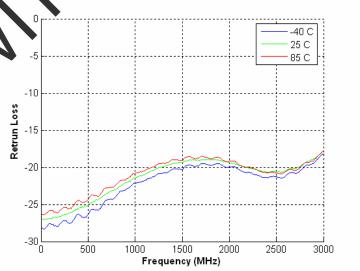




Figure 22. Package Drawing

8-lead MSOP

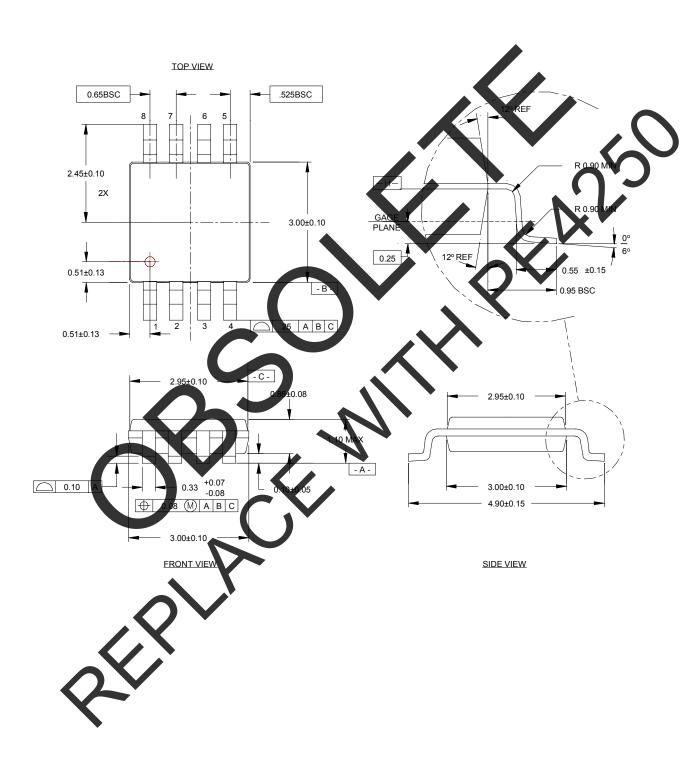




Figure 23. Tape and Reel Specifications

8-lead MSOP

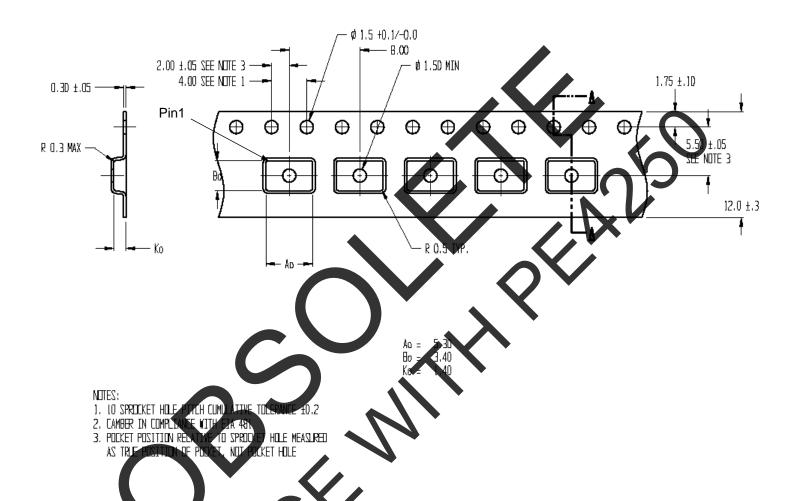


Table 7. Ordering Information

Order Code	Part Marking	Description	Package	Shipping Method
4272-01	4272	PE4272-08MSOP-50A	8-lead MSOP	50 units / Tube
4272-02	4272	PE4272-08MSOP-2000C	8-lead MSOP	2000 units / T&R
4272-00	PE4272-EK	PE4272-08MSOP-EK	Evaluation Kit	1 / Box
4272-51	4272	PE4272G-08MSOP-50A	Green 8-lead MSOP	50 units / Tube
4272-52	4272	PE4272G-08MSOP-2000C	Green 8-lead MSOP	2000 units / T&R



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